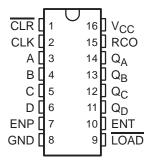
SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

- Wide Operating Voltage Range of 2 V to 6 V
- **Outputs Can Drive Up To 10 LSTTL Loads**
- Low Power Consumption, 80-µA Max ICC
- Typical  $t_{nd} = 14 \text{ ns}$
- ±4-mA Output Drive at 5 V
- Low Input Current of 1 µA Max
- Internal Look-Ahead for Fast Counting
- **Carry Output for n-Bit Cascading**
- **Synchronous Counting**
- Synchronously Programmable

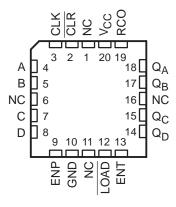
### description/ordering information

These synchronous, presettable counters feature an internal carry look-ahead for application in high-speed counting designs. The 'HC163 devices are 4-bit binary counters. Synchronous operation is provided by having all flip-flops clocked simultaneously so that the outputs change coincident with each other when instructed by the count-enable (ENP, ENT) inputs and internal gating. This mode of operation eliminates the output counting spikes normally associated with synchronous (ripple-clock) counters. A buffered clock (CLK) input triggers the four flip-flops on the rising (positive-going) edge of the clock waveform.

### SN54HC163...J OR W PACKAGE SN74HC163...D, DB, N, NS, OR PW PACKAGE (TOP VIEW)



SN54HC163...FK PACKAGE (TOP VIEW)



NC - No internal connection

### ORDERING INFORMATION

TA	PACKA	GE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N T		SN74HC163N	SN74HC163N
-40°C to 85°C		Tube of 40	SN74HC163D	
	SOIC - D	Reel of 2500	SN74HC163DR	HC163
		Reel of 250	SN74HC163DT	
	SOP - NS	Reel of 2000	SN74HC163NSR	HC163
	SSOP - DB	Reel of 2000	SN74HC163DBR	HC163
		Tube of 90	SN74HC163PW	
	TSSOP - PW	Reel of 2000	SN74HC163PWR	HC163
		Reel of 250	SN74HC163PWT	
	CDIP – J	Tube of 25	SNJ54HC163J	SNJ54HC163J
–55°C to 125°C	CFP – W	Tube of 150	SNJ54HC163W	SNJ54HC163W
	LCCC – FK	Tube of 55	SNJ54HC163FK	SNJ54HC163FK

<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



## SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

### description/ordering information (continued)

These counters are fully programmable; that is, they can be preset to any number between 0 and 9 or 15. As presetting is synchronous, setting up a low level at the load input disables the counter and causes the outputs to agree with the setup data after the next clock pulse, regardless of the levels of the enable inputs.

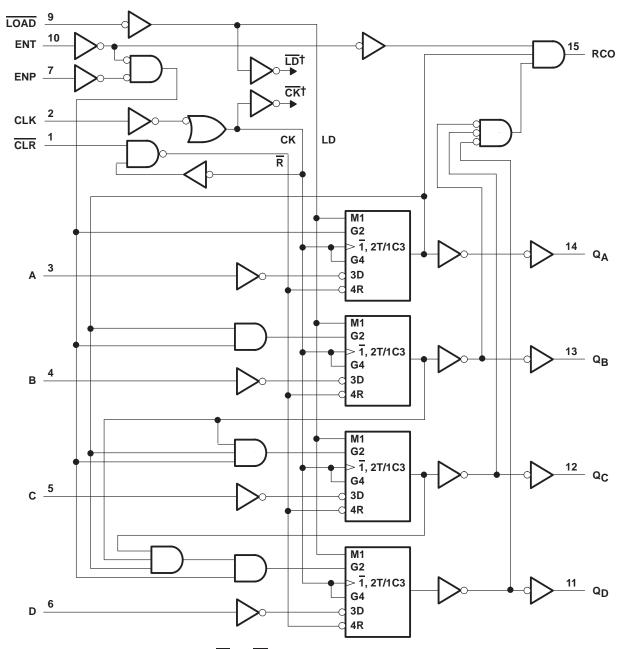
The clear function for the 'HC163 devices is synchronous. A low level at the clear ( $\overline{\text{CLR}}$ ) input sets all four of the flip-flop outputs low after the next low-to-high transition of CLK, regardless of the levels of the enable inputs. This synchronous clear allows the count length to be modified easily by decoding the Q outputs for the maximum count desired. The active-low output of the gate used for decoding is connected to  $\overline{\text{CLR}}$  to synchronously clear the counter to 0000 (LLLL).

The carry look-ahead circuitry provides for cascading counters for n-bit synchronous applications without additional gating. ENP, ENT, and a ripple-carry output (RCO) are instrumental in accomplishing this function. Both ENP and ENT must be high to count, and ENT is fed forward to enable RCO. Enabling RCO produces a high-level pulse while the count is maximum (9 or 15 with  $Q_A$  high). This high-level overflow ripple-carry pulse can be used to enable successive cascaded stages. Transitions at ENP or ENT are allowed, regardless of the level of CLK.

These counters feature a fully independent clock circuit. Changes at control inputs (ENP, ENT, or  $\overline{\text{LOAD}}$ ) that modify the operating mode have no effect on the contents of the counter until clocking occurs. The function of the counter (whether enabled, disabled, loading, or counting) is dictated solely by the conditions meeting the stable setup and hold times.



## logic diagram (positive logic)

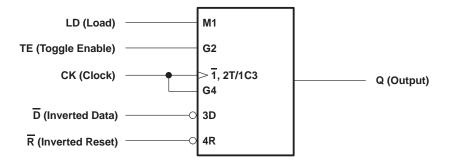


<sup>†</sup> For simplicity, routing of complementary signals  $\overline{LD}$  and  $\overline{CK}$  is not shown on this overall logic diagram. The uses of these signals are shown on the logic diagram of the D/T flip-flops.

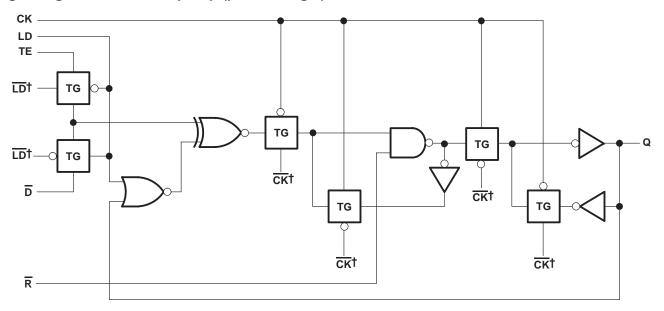
Pin numbers shown are for the D, DB, J, N, NS, PW, and W packages.

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

## logic symbol, each D/T flip-flop



## logic diagram, each D/T flip-flop (positive logic)

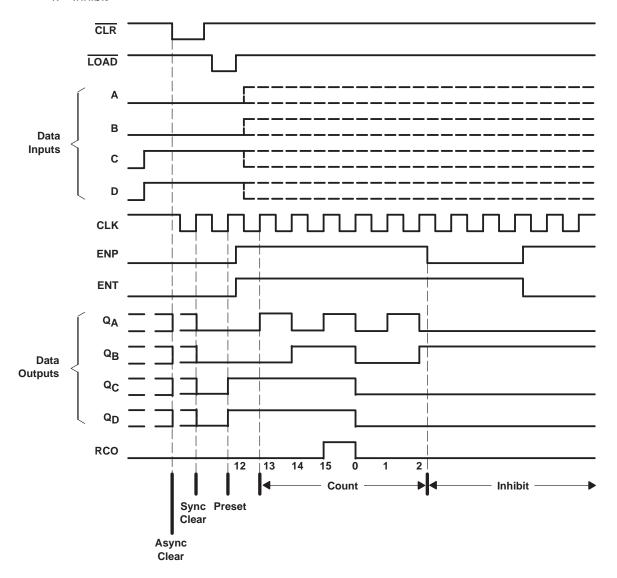


 $<sup>^\</sup>dagger$  The origins of  $\overline{\text{LD}}$  and  $\overline{\text{CK}}$  are shown in the logic diagram of the overall device.

## typical clear, preset, count, and inhibit sequence

The following sequence is illustrated below:

- 1. Clear outputs to zero (synchronous)
- 2. Preset to binary 12
- 3. Count to 13, 14, 15, 0, 1, and 2
- 4. Inhibit



## SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>		$-0.5 \text{ V to 7 V}$
Input clamp current, $I_{IK}$ ( $V_I < 0$ or $V_I > V_{CC}$ ) (see	ee Note 1)	±20 mA
Output clamp current, IOK (VO < 0 or VO > VCO	c) (see Note 1)	±20 mA
Continuous output current, $I_O(V_O = 0 \text{ to } V_{CC})$		
Continuous current through V <sub>CC</sub> or GND		
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	: D package	73°C/W
, ,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DB package	82°C/W
	N package	67°C/W
	NS package	64°C/W
	PW package	108°C/W
Storage temperature range, T <sub>sto</sub>		-65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## recommended operating conditions (see Note 3)

			SI	SN54HC163		SN	174HC16	3		
			MIN	NOM	MAX	MIN	NOM	MAX	UNIT	
Vcc	Supply voltage		2	5	6	2	5	6	V	
		V <sub>CC</sub> = 2 V	1.5			1.5				
V <sub>IH</sub> Hig	High-level input voltage	V <sub>CC</sub> = 4.5 V	3.15			3.15			V	
		V <sub>CC</sub> = 6 V	4.2			4.2				
	Low-level input voltage	V <sub>CC</sub> = 2 V			0.5			0.5	V	
٧ <sub>IL</sub>		V <sub>CC</sub> = 4.5 V			1.35			1.35		
		V <sub>CC</sub> = 6 V			1.8			1.8		
VI	Input voltage		0		VCC	0		VCC	V	
VO	Output voltage		0		VCC	0		VCC	V	
		V <sub>CC</sub> = 2 V			1000			1000		
Δt/Δv‡	Input transition rise/fall time	V <sub>CC</sub> = 4.5 V			500			500	ns	
		V <sub>CC</sub> = 6 V			400			400		
TA	Operating free-air temperature		-55		125	-40		85	°C	

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.



NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>2.</sup> The package thermal impedance is calculated in accordance with JESD 51-7.

<sup>‡</sup> If this device is used in the threshold region (from V<sub>IL</sub>max = 0.5 V to V<sub>IH</sub>min = 1.5 V), there is a potential to go into the wrong state from induced grounding, causing double clocking. Operating with the inputs at t<sub>t</sub> = 1000 ns and V<sub>CC</sub> = 2 V does not damage the device; however, functionally, the CLK inputs are not ensured while in the shift, count, or toggle operating modes.

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

## electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

24244555	7507.00	TEST CONDITIONS		Т	A = 25°C	;	SN54H	IC163	SN74HC163		
PARAMETER	IESI CC	ONDITIONS	VCC	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	1.9	1.998		1.9		1.9		
		$I_{OH} = -20  \mu A$	4.5 V	4.4	4.499		4.4		4.4		
Voн	VI = VIH or VIL		6 V	5.9	5.999		5.9		5.9		V
		$I_{OH} = -4 \text{ mA}$	4.5 V	3.98	4.3		3.7		3.84		
		$I_{OH} = -5.2 \text{ mA}$	6 V	5.48	5.8		5.2		5.34		
			2 V		0.002	0.1		0.1		0.1	
	VI = VIH or VIL	I <sub>OL</sub> = 20 μA	4.5 V		0.001	0.1		0.1		0.1	
VoL			6 V		0.001	0.1		0.1		0.1	V
		I <sub>OL</sub> = 4 mA	4.5 V		0.17	0.26		0.4		0.33	
		$I_{OL} = 5.2 \text{ mA}$	6 V		0.15	0.26		0.4		0.33	
lį	$V_I = V_{CC}$ or 0		6 V		±0.1	±100		±1000		±1000	nA
Icc	$V_I = V_{CC}$ or 0,	IO = 0	6 V			8		160		80	μΑ
Ci			2 V to 6 V		3	10		10		10	pF

# timing requirements over recommended operating free-air temperature range (unless otherwise noted)

				T <sub>A</sub> =	25°C	SN54H	IC163	SN74HC163		
			vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V		6		4.2		5	
fclock	Clock frequency		4.5 V		31		21		25	MHz
			6 V		36		25		29	
			2 V	80		120		100		
t <sub>w</sub>	Pulse duration	CLK high or low	4.5 V	16		24		20		ns
			6 V	14		20		17		
		2 V	150		225		190			
		A, B, C, or D	4.5 V	30		45		38		
			6 V	26		38		32		
			2 V	135		205		170		ns
		LOAD low	4.5 V	27		41		34		
			6 V	23		35		29		
			2 V	170		255		215		
t <sub>su</sub>	Setup time before CLK↑	ENP, ENT	4.5 V	34		51		43		
			6 V	29		43		37		
			2 V	160		240		200		
		CLR low	4.5 V	32		48		40		
			6 V	27		41		34		
			2 V	160		240		200		
		CLR inactive	4.5 V	32		48		40		
			6 V	27		41		34		
			2 V	0		0		0		
th	Hold time, all synchronous inpu	ts after CLK↑	4.5 V	0		0		0		ns
			6 V	0		0		0		

## SN54HC163, SN74HC163 4-BIT SYNCHRONOUS BINARY COUNTERS

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

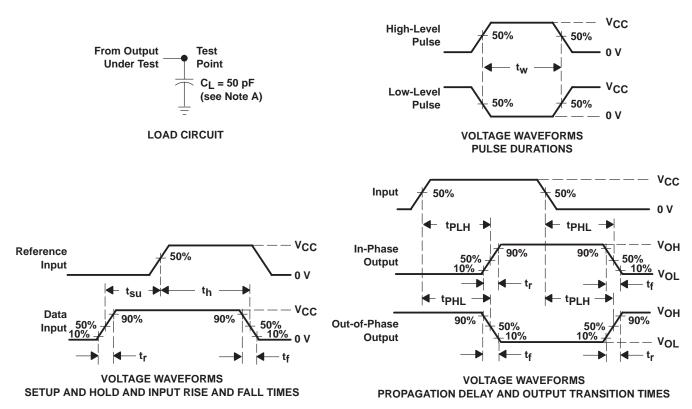
# switching characteristics over recommended operating free-air temperature range, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

BABAMETER	FROM	то	.,	T,	ղ = 25°C	;	SN54H	C163	SN74HC163		
PARAMETER	(INPUT)	(OUTPUT)	vcc	MIN	TYP	MAX	MIN	MAX	MIN	MAX	UNIT
			2 V	6	14		4.2		5		
f <sub>max</sub>			4.5 V	31	40		21		25		MHz
			6 V	36	44		25		29		
			2 V		83	215		325		270	
	CLK	RCO	4.5 V		24	43		65		54	
			6 V		20	37		55		46	
		Any Q	2 V		80	205		310		255	ns
<sup>t</sup> pd			4.5 V		25	41		62		51	
·			6 V		21	35		53		43	
			2 V		62	195		295		245	
	ENT	RCO	4.5 V		17	39		59		49	
			6 V		14	33		50		42	
			2 V		38	75		110		95	
t <sub>t</sub>		Any	4.5 V		8	15		22		19	ns
			6 V		6	13		19		16	

## operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CONDITIONS	TYP	UNIT
C <sub>pd</sub>	Power dissipation capacitance	No load	60	pF

### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>I</sub> includes probe and test-fixture capacitance.

- B. Phase relationships between waveforms were chosen arbitrarily. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  1 MHz,  $Z_O = 50 \ \Omega$ ,  $t_f = 6 \ ns$ ,  $t_f = 6 \ ns$ .
- C. For clock inputs,  $f_{\text{max}}$  is measured when the input duty cycle is 50%.
- D. The outputs are measured one at a time with one input transition per measurement.
- E. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

SCLS298D - JANUARY 1996 - REVISED - OCTOBER 2003

### **APPLICATION INFORMATION**

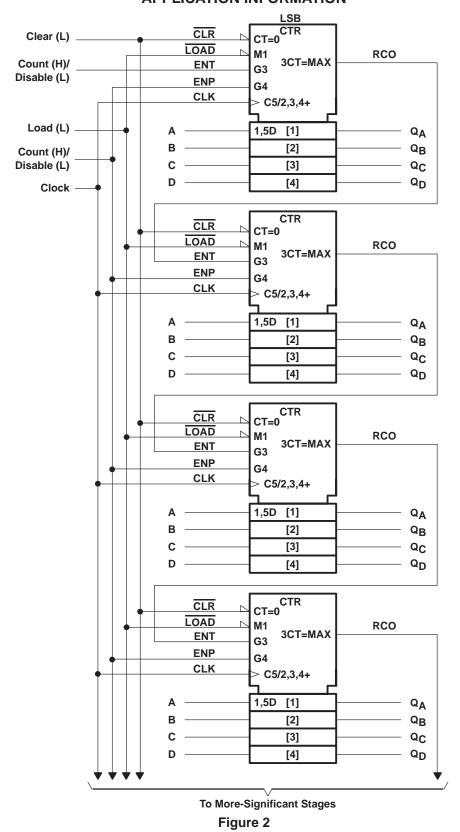
### n-bit synchronous counters

This application demonstrates how the look-ahead carry circuit can be used to implement a high-speed n-bit counter. The 'HC163 devices count in binary. Virtually any count mode (modulo-N, N<sub>1</sub>-to-N<sub>2</sub>, N<sub>1</sub>-to-maximum) can be used with this fast look-ahead circuit.

The application circuit shown in Figure 2 is not valid for clock frequencies above 18 MHz (at  $25^{\circ}$ C and  $4.5\text{-V V}_{CC}$ ). The reason for this is that there is a glitch that is produced on the second stage's RCO and every succeeding stage's RCO. This glitch is common to all HC vendors that Texas Instruments has evaluated, in addition to the bipolar equivalents (LS, ALS, AS).



## **APPLICATION INFORMATION**

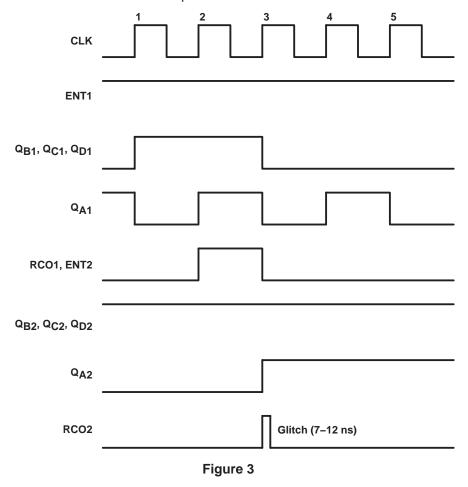


TEXAS INSTRUMENTS

### **APPLICATION INFORMATION**

### n-bit synchronous counters (continued)

The glitch on RCO is caused because the propagation delay of the rising edge of  $Q_A$  of the second stage is shorter than the propagation delay of the falling edge of ENT. RCO is the product of ENT,  $Q_A$ ,  $Q_B$ ,  $Q_C$ , and  $Q_D$  (ENT  $\times$   $Q_A \times Q_B \times Q_C \times Q_D$ ). The resulting glitch is about 7–12 ns in duration. Figure 3 shows the condition in which the glitch occurs. For simplicity, only two stages are being considered, but the results can be applied to other stages.  $Q_B$ ,  $Q_C$ , and  $Q_D$  of the first and second stage are at logic one, and  $Q_A$  of both stages are at logic zero (1110 1110) after the first clock pulse. On the rising edge of the second clock pulse,  $Q_A$  and RCO of the first stage go high. On the rising edge of the third clock pulse,  $Q_A$  and RCO of the first stage return to a low level, and  $Q_A$  of the second stage goes to a high level. At this time, the glitch on RCO of the second stage appears because of the race condition inside the chip.



The glitch causes a problem in the next stage (stage three) if the glitch is still present when the next rising clock edge appears (clock pulse 4). To ensure that this does not happen, the clock frequency must be less than the inverse of the sum of the clock-to-RCO propagation delay and the glitch duration ( $t_g$ ). In other words,  $t_{max} = 1/(t_{pd} \text{ CLK-to-RCO} + t_g)$ . For example, at 25°C at 4.5-V  $t_{CC}$ , the clock-to-RCO propagation delay is 43 ns and the maximum duration of the glitch is 12 ns. Therefore, the maximum clock frequency that the cascaded counters can use is 18 MHz. The following tables contain the  $t_{clock}$ ,  $t_{w}$ , and  $t_{max}$  specifications for applications that use more than two 'HC163 devices cascaded together.

#### **APPLICATION INFORMATION**

### n-bit synchronous counters (continued)

## timing requirements over recommended operating free-air temperature range (unless otherwise noted)

		.,	T <sub>A</sub> = 25°C		SN54HC163		SN74HC163		
		vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
		2 V		3.6		2.5		2.9	
f <sub>clock</sub> Clock freque	ock frequency	4.5 V		18		12		14	MHz
		6 V		21		14		17	
t <sub>w</sub> Pu	Pulse duration, CLK high or low	2 V	140		200		170		ns
		4.5 V	28		40		36		
		6 V	24	·	36		30		

## switching characteristics over recommended operating free-air temperature range, $C_L = 50 \text{ pF}$ (unless otherwise noted) (see Note 4)

DADAMETED	FROM	TO (OUTPUT)	,,	T <sub>A</sub> = 25°C		SN54HC163		SN74HC163		
PARAMETER	(INPUT)		vcc	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
f <sub>max</sub>			2 V	3.6		2.5		2.9		
			4.5 V	18		12		14		MHz
			6 V	21		14		17		

NOTE 4: These limits apply only to applications that use more than two 'HC163 devices cascaded together.

If the 'HC163 devices are used as a single unit, or only two cascaded together, then the maximum clock frequency that the devices can use is not limited because of the glitch. In these situations, the devices can be operated at the maximum specifications.

A glitch can appear on RCO of a single 'HC163 device, depending on the relationship of ENT to CLK. Any application that uses RCO to drive any input, except an ENT of another cascaded 'HC163 device, must take this into consideration.

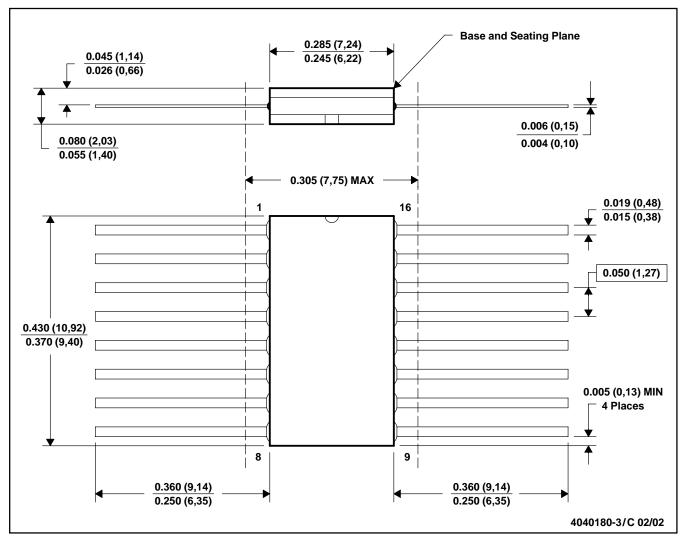
## 14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

### W (R-GDFP-F16)

### **CERAMIC DUAL FLATPACK**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP-1F16 and JEDEC MO-092AC

### FK (S-CQCC-N\*\*)

### **28 TERMINAL SHOWN**

### **LEADLESS CERAMIC CHIP CARRIER**



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. The terminals are gold plated.
- E. Falls within JEDEC MS-004



## N (R-PDIP-T\*\*)

## PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN

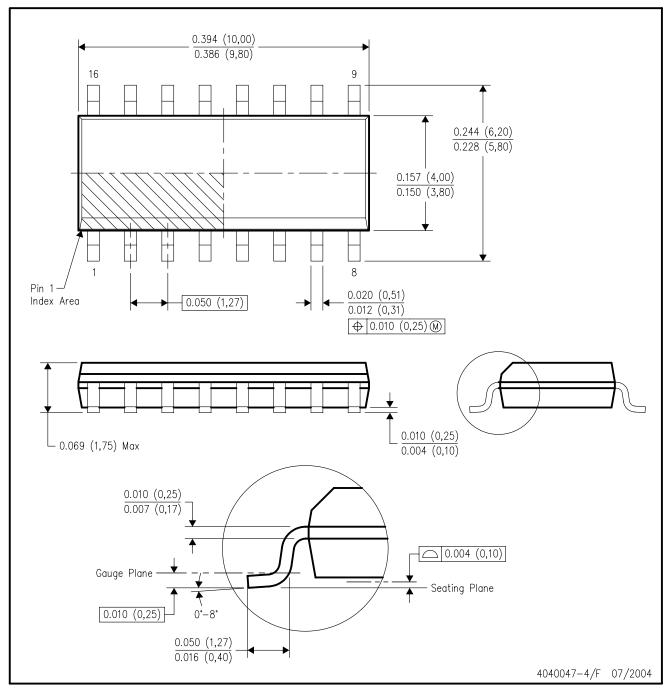


- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



## D (R-PDSO-G16)

## PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-012 variation AC.



## **MECHANICAL DATA**

## NS (R-PDSO-G\*\*)

## 14-PINS SHOWN

### PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



## DB (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE

### **28 PINS SHOWN**



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

## PW (R-PDSO-G\*\*)

### 14 PINS SHOWN

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

#### **IMPORTANT NOTICE**

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products		Applications	
Amplifiers	amplifier.ti.com	Audio	www.ti.com/audio
Data Converters	dataconverter.ti.com	Automotive	www.ti.com/automotive
DSP	dsp.ti.com	Broadband	www.ti.com/broadband
Interface	interface.ti.com	Digital Control	www.ti.com/digitalcontrol
Logic	logic.ti.com	Military	www.ti.com/military
Power Mgmt	power.ti.com	Optical Networking	www.ti.com/opticalnetwork
Microcontrollers	microcontroller.ti.com	Security	www.ti.com/security
		Telephony	www.ti.com/telephony
		Video & Imaging	www.ti.com/video
		Wireless	www.ti.com/wireless

Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265

Copyright © 2004, Texas Instruments Incorporated